

Appln. No.: 10/656,392  
Amendment Dated November 21, 2006  
Reply to Office Action of August 30, 2006

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MKPA-107US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appln. No: 10/656,392  
Applicant: Trebor Heminway et al.  
Filed: 09/05/2003  
Title: SOLDER PREFORM FOR LOW HEAT STRESS LASER SOLDER ATTACHMENT  
TC/A.U.: 1725  
Examiner: Jonathan J. Johnson  
Confirmation No.: 9588  
Docket No.: MKPA-107US

**AMENDMENT UNDER 37 C.F.R. § 1.116**

**Expedited Procedure**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action dated August 30, 2006, please amend the above-identified application as follows:

- ☐ **Amendments to the Specification** begin on page \_\_\_\_\_ of this paper.
- ☒ **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.
- ☐ **Amendments to the Drawings** begin on page \_\_\_\_\_ of this paper and include an attached replacement sheet(s).
- ☐ **Amendments to the Abstract** are on page \_\_\_\_\_ of this paper. A clean version of the Abstract is on page \_\_\_\_\_ of this paper.
- ☒ **Remarks/Arguments** begin on page 5 of this paper.